

Layers: 2
Material: FR4
Finished Thickness: 1.57mm +/- 10%
Outer Layer Copper Thickness: 1oz
Finish: ENIG (Au:2-5u")
Soldermask (Color): Both Sides, LPI (Black)
Silkscreen (Color): Both Sides, White

Electrical test

FINISH: THIS BOARD SHALL BE IMMERSION GOLD PLATED ACCORDING TO IPC-6012.
THICKNESS SHALL BE .050uM OVER 3-6uM NICKEL.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED, EXCEPT VIAS .500 FINISH OR SMALLER.

Layer Key:

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*.GM4: Board Outline

*.TXT: NC Drill File

*.GTP: Top Paste

*.GTO: Top Silkscreen

*.GTS: Top Soldermask

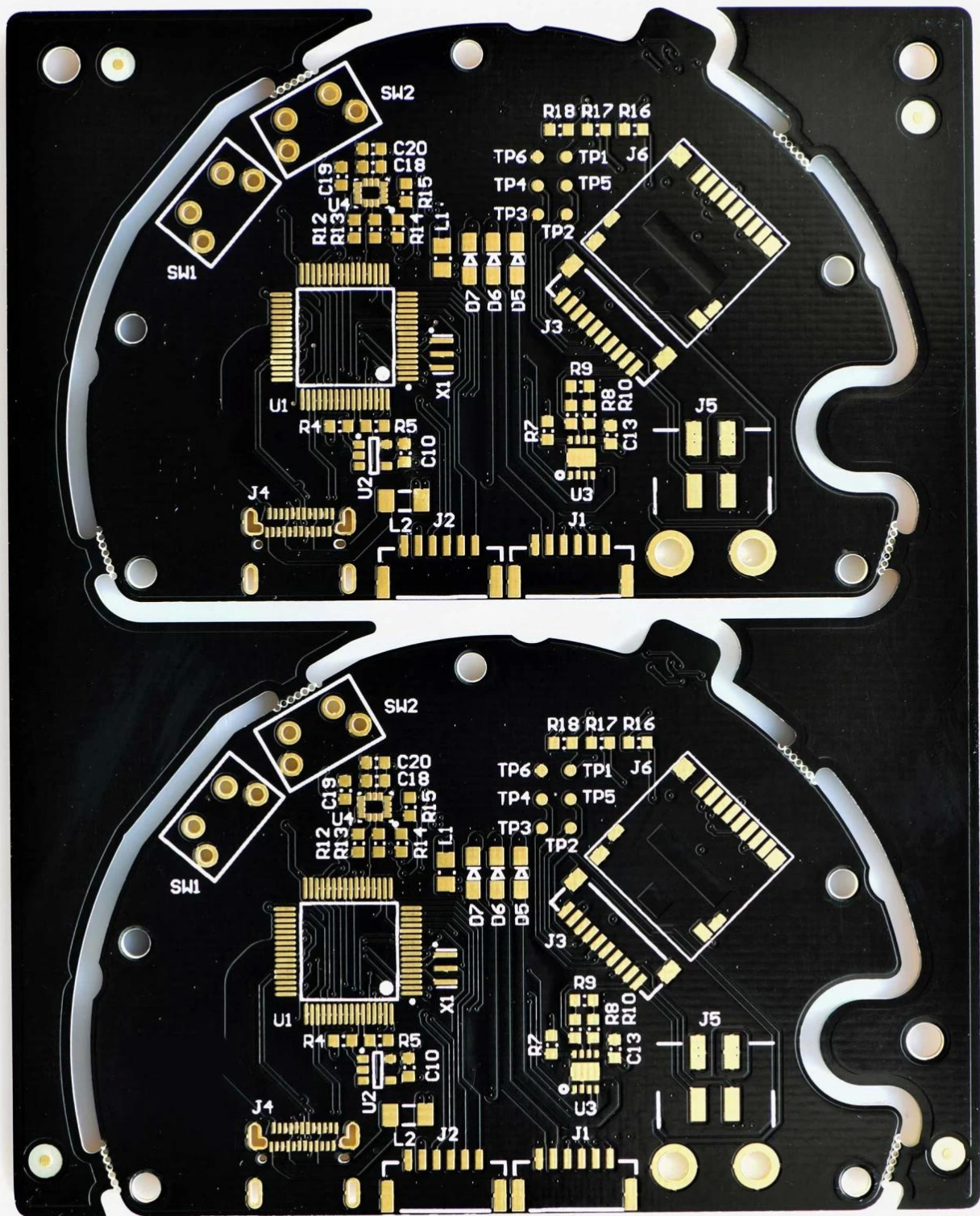
*.GTL: Top Copper Layer

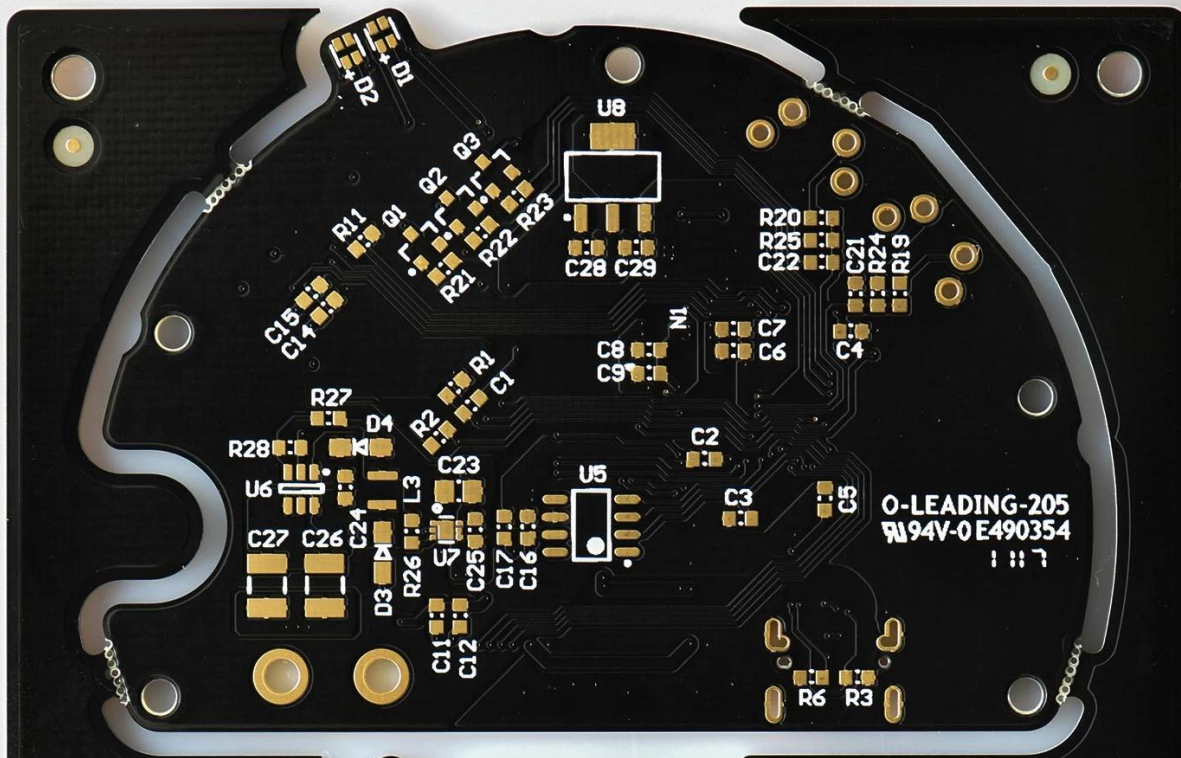
*.GBL: Bottom Copper Layer

*.GBS: Bottom Soldermask

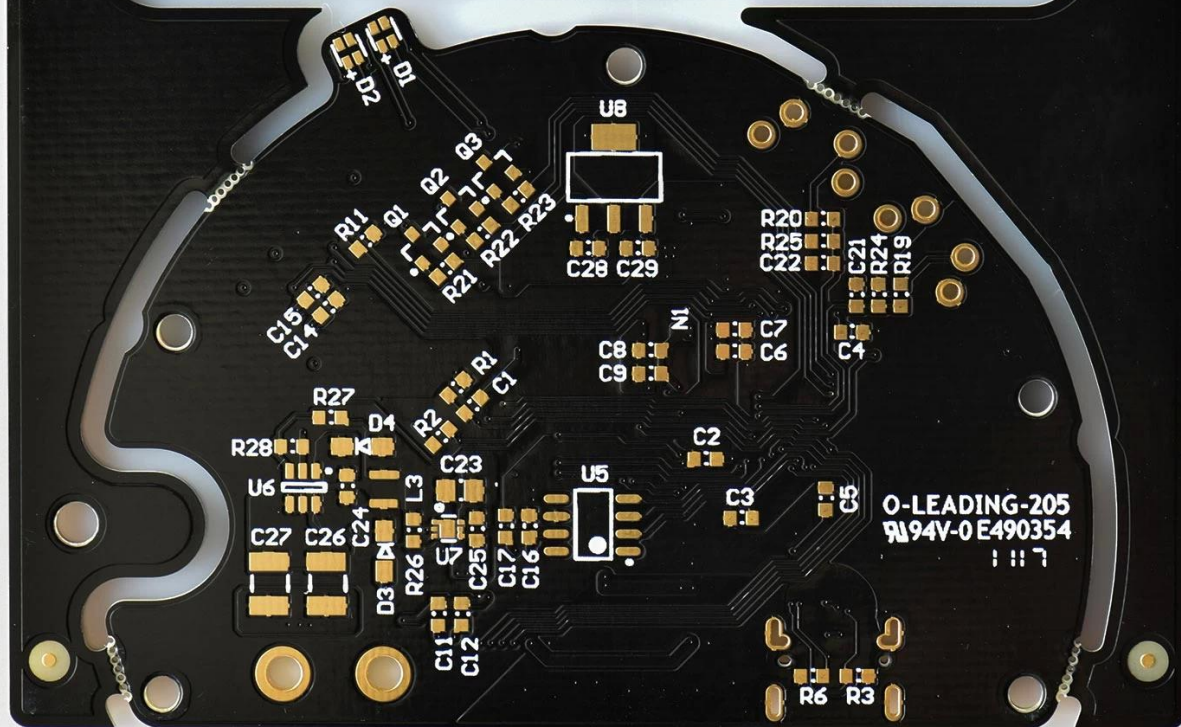
*.GBO: Bottom Silkscreen

*.GBP: Bottom Paste





O-LEADING-205
94V-0 E490354
1 1 7



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